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Details

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Product Status	Last Time Buy
Core Processor	C166SV2
Core Size	16-Bit
Speed	40MHz
Connectivity	CANbus, EBI/EMI, I ² C, SLDM, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	99
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 2.7V
Data Converters	A/D 12x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	PG-P-TQFP-144-19
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc161cj16f40fbbfxqma1

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Table of Contents

Table of Contents

1	Summary of Features	4
2 2.1	General Device Information	7 7 0
2.2		0
3 3.1 3.2 3.3 3.4 3.5 3.6 3.7	Functional Description Memory Subsystem and Organization External Bus Controller Central Processing Unit (CPU) Interrupt System On-Chip Debug Support (OCDS) Capture/Compare Units (CAPCOM1/2) General Purpose Timer (GPT12E) Unit	19 20 22 24 26 31 32
3.8	Real Time Clock	39
3.9 3.10 3.11 3.12 3.13 3.14 3.15 3.16 3.17	A/D Converter A Asynchronous/Synchronous Serial Interfaces (ASC0/ASC1) A High Speed Synchronous Serial Channels (SSC0/SSC1) A Serial Data Link Module (SDLM) A TwinCAN Module A IIC Bus Module A Watchdog Timer A Clock Generation A Parallel Ports A	41 42 43 44 45 46 47 48 48
3.18 3.19	Power Management	50 51
4 4.1 4.2 4.3 4.4 4.4.1 4.4.2 4.4.3 4.4.3 4.4.4 4.4.5	Electrical Parameters Electrical Parameters General Parameters Electrical Parameters DC Parameters Electrical Parameters Analog/Digital Converter Parameters Electrical Parameters AC Parameters Electrical Converter Parameters Definition of Internal Timing External Clock Drive XTAL1 Testing Waveforms External Bus Timing	54 57 63 66 70 71 72 73
5 5.1 5.2	Package and Reliability 8 Packaging 8 Flash Memory Parameters 8	83 83 85



16-Bit Single-Chip Microcontroller with C166SV2 Core XC166 Family

1 Summary of Features

- High Performance 16-bit CPU with 5-Stage Pipeline
 - 25 ns Instruction Cycle Time at 40 MHz CPU Clock (Single-Cycle Execution)
 - 1-Cycle Multiplication (16 \times 16 bit), Background Division (32 / 16 bit) in 21 Cycles
 - 1-Cycle Multiply-and-Accumulate (MAC) Instructions
 - Enhanced Boolean Bit Manipulation Facilities
 - Zero-Cycle Jump Execution
 - Additional Instructions to Support HLL and Operating Systems
 - Register-Based Design with Multiple Variable Register Banks
 - Fast Context Switching Support with Two Additional Local Register Banks
 - 16 Mbytes Total Linear Address Space for Code and Data
 - 1024 Bytes On-Chip Special Function Register Area (C166 Family Compatible)
- 16-Priority-Level Interrupt System with 73 Sources, Sample-Rate down to 50 ns
- 8-Channel Interrupt-Driven Single-Cycle Data Transfer Facilities via Peripheral Event Controller (PEC), 24-Bit Pointers Cover Total Address Space
- Clock Generation via on-chip PLL (factors 1:0.15 ... 1:10), or via Prescaler (factors 1:1 ... 60:1)
- On-Chip Memory Modules
 - 2 Kbytes On-Chip Dual-Port RAM (DPRAM)
 - 4 Kbytes On-Chip Data SRAM (DSRAM)
 - 2 Kbytes On-Chip Program/Data SRAM (PSRAM)
 - 128 Kbytes On-Chip Program Memory (Flash Memory)
- On-Chip Peripheral Modules
 - 12-Channel A/D Converter with Programmable Resolution (10-bit or 8-bit) and Conversion Time (down to 2.55 μs or 2.15 $\mu s)$
 - Two 16-Channel General Purpose Capture/Compare Units (32 Input/Output Pins)
 - Multi-Functional General Purpose Timer Unit with 5 Timers
 - Two Synchronous/Asynchronous Serial Channels (USARTs)
 - Two High-Speed-Synchronous Serial Channels
 - On-Chip TwinCAN Interface (Rev. 2.0B active) with 32 Message Objects (Full CAN/Basic CAN) on Two CAN Nodes, and Gateway Functionality
 - Serial Data Link Module (SDLM), compliant with J1850, supporting Class 2
 - IIC Bus Interface (10-bit addressing, 400 kbit/s) with 3 Channels (multiplexed)
 - On-Chip Real Time Clock, Driven by Dedicated Oscillator
- Idle, Sleep, and Power Down Modes with Flexible Power Management
- Programmable Watchdog Timer and Oscillator Watchdog



Summary of Features

Table 1 XC161 Derivative Synopsis

Derivative ¹⁾	Temp. Range	Program Memory	On-Chip RAM	Interfaces
SAK-XC161CJ-16F40F, SAK-XC161CJ-16F20F	-40 °C to 125 °C	128 Kbytes Flash	2 Kbytes DPRAM, 4 Kbytes DSRAM, 2 Kbytes PSRAM	ASC0, ASC1, SSC0, SSC1, CAN0, CAN1, SDLM, IIC
SAF-XC161CJ-16F40F, SAF-XC161CJ-16F20F	-40 °C to 85 °C	128 Kbytes Flash	2 Kbytes DPRAM, 4 Kbytes DSRAM, 2 Kbytes PSRAM	ASC0, ASC1, SSC0, SSC1, CAN0, CAN1, SDLM, IIC

1) This Data Sheet is valid for devices starting with and including design step BB.



General Device Information

2 General Device Information

2.1 Introduction

The XC161 derivatives are high-performance members of the Infineon XC166 Family of full featured single-chip CMOS microcontrollers. These devices extend the functionality and performance of the C166 Family in terms of instructions (MAC unit), peripherals, and speed. They combine high CPU performance (up to 40 million instructions per second) with high peripheral functionality and enhanced IO-capabilities. They also provide clock generation via PLL and various on-chip memory modules such as program Flash, program RAM, and data RAM.



Figure 1 Logic Symbol



General Device Information

Table 2	le 2 Pin Definitions and Functions (cont'd)				
Sym- bol	Pin Num.	Input Outp.	Function		
P2		IO	Port 2 is an programme state) or or driver). The or special) The followi	n 8-bit bidirectional I/O port. Each pin can be ed for input (output driver in high-impedance utput (configurable as push/pull or open drain e input threshold of Port 2 is selectable (standard ing Port 2 pins also serve for alternate functions:	
P2.8	49	I/O I	CC8IO EX0IN	CAPCOM1: CC8 Capture Inp./Compare Output, Fast External Interrupt 0 Input (default pin)	
P2.9	50	I/O I	CC9IO EX1IN	CAPCOM1: CC9 Capture Inp./Compare Output, Fast External Interrupt 1 Input (default pin)	
P2.10	51	I/O I	CC10IO EX2IN	CAPCOM1: CC10 Capture Inp./Compare Outp., Fast External Interrupt 2 Input (default pin)	
P2.11	52	I/O I	CC11IO EX3IN	CAPCOM1: CC11 Capture Inp./Compare Outp., Fast External Interrupt 3 Input (default pin)	
P2.12	53	I/O I	CC12IO EX4IN	CAPCOM1: CC12 Capture Inp./Compare Outp., Fast External Interrupt 4 Input (default pin)	
P2.13	54	I/O I	CC13IO EX5IN	CAPCOM1: CC13 Capture Inp./Compare Outp., Fast External Interrupt 5 Input (default pin)	
P2.14	55	I/O I	CC14IO EX6IN	CAPCOM1: CC14 Capture Inp./Compare Outp., Fast External Interrupt 6 Input (default pin)	
P2.15	56	I/O I I	CC15IO EX7IN T7IN	CAPCOM1: CC15 Capture Inp./Compare Outp., Fast External Interrupt 7 Input (default pin), CAPCOM2: Timer T7 Count Input	
TRST	57	1	Test-Syste TRST shou edge of RS this case, I debug syst	em Reset Input. For normal system operation, pin uld be held low. A high level at this pin at the rising STIN activates the XC164CM's debug system. In pin TRST must be driven low once to reset the tem.	



and rotate instructions are always processed during one machine cycle independent of the number of bits to be shifted. Also multiplication and most MAC instructions execute in one single cycle. All multiple-cycle instructions have been optimized so that they can be executed very fast as well: for example, a division algorithm is performed in 18 to 21 CPU cycles, depending on the data and division type. Four cycles are always visible, the rest runs in the background. Another pipeline optimization, the branch target prediction, allows eliminating the execution time of branch instructions if the prediction was correct.

The CPU has a register context consisting of up to three register banks with 16 wordwide GPRs each at its disposal. The global register bank is physically allocated within the onchip DPRAM area. A Context Pointer (CP) register determines the base address of the active global register bank to be accessed by the CPU at any time. The number of register banks is only restricted by the available internal RAM space. For easy parameter passing, a register bank may overlap others.

A system stack of up to 32 Kwords is provided as a storage for temporary data. The system stack can be allocated to any location within the address space (preferably in the on-chip RAM area), and it is accessed by the CPU via the stack pointer (SP) register. Two separate SFRs, STKOV and STKUN, are implicitly compared against the stack pointer value upon each stack access for the detection of a stack overflow or underflow.

The high performance offered by the hardware implementation of the CPU can efficiently be utilized by a programmer via the highly efficient XC161 instruction set which includes the following instruction classes:

- Standard Arithmetic Instructions
- DSP-Oriented Arithmetic Instructions
- Logical Instructions
- Boolean Bit Manipulation Instructions
- Compare and Loop Control Instructions
- Shift and Rotate Instructions
- Prioritize Instruction
- Data Movement Instructions
- System Stack Instructions
- Jump and Call Instructions
- Return Instructions
- System Control Instructions
- Miscellaneous Instructions

The basic instruction length is either 2 or 4 bytes. Possible operand types are bits, bytes and words. A variety of direct, indirect or immediate addressing modes are provided to specify the required operands.



3.7 General Purpose Timer (GPT12E) Unit

The GPT12E unit represents a very flexible multifunctional timer/counter structure which may be used for many different time related tasks such as event timing and counting, pulse width and duty cycle measurements, pulse generation, or pulse multiplication.

The GPT12E unit incorporates five 16-bit timers which are organized in two separate modules, GPT1 and GPT2. Each timer in each module may operate independently in a number of different modes, or may be concatenated with another timer of the same module.

Each of the three timers T2, T3, T4 of **module GPT1** can be configured individually for one of four basic modes of operation, which are Timer, Gated Timer, Counter, and Incremental Interface Mode. In Timer Mode, the input clock for a timer is derived from the system clock, divided by a programmable prescaler, while Counter Mode allows a timer to be clocked in reference to external events.

Pulse width or duty cycle measurement is supported in Gated Timer Mode, where the operation of a timer is controlled by the 'gate' level on an external input pin. For these purposes, each timer has one associated port pin (TxIN) which serves as gate or clock input. The maximum resolution of the timers in module GPT1 is 4 system clock cycles.

The count direction (up/down) for each timer is programmable by software or may additionally be altered dynamically by an external signal on a port pin (TxEUD) to facilitate e.g. position tracking.

In Incremental Interface Mode the GPT1 timers (T2, T3, T4) can be directly connected to the incremental position sensor signals A and B via their respective inputs TxIN and TxEUD. Direction and count signals are internally derived from these two input signals, so the contents of the respective timer Tx corresponds to the sensor position. The third position sensor signal TOP0 can be connected to an interrupt input.

Timer T3 has an output toggle latch (T3OTL) which changes its state on each timer overflow/underflow. The state of this latch may be output on pin T3OUT e.g. for time out monitoring of external hardware components. It may also be used internally to clock timers T2 and T4 for measuring long time periods with high resolution.

In addition to their basic operating modes, timers T2 and T4 may be configured as reload or capture registers for timer T3. When used as capture or reload registers, timers T2 and T4 are stopped. The contents of timer T3 is captured into T2 or T4 in response to a signal at their associated input pins (TxIN). Timer T3 is reloaded with the contents of T2 or T4 triggered either by an external signal or by a selectable state transition of its toggle latch T3OTL. When both T2 and T4 are configured to alternately reload T3 on opposite state transitions of T3OTL with the low and high times of a PWM signal, this signal can be constantly generated without software intervention.









3.8 Real Time Clock

The Real Time Clock (RTC) module of the XC161 is directly clocked via a separate clock driver either with the on-chip auxiliary oscillator frequency ($f_{\text{RTC}} = f_{\text{OSCa}}$) or with the prescaled on-chip main oscillator frequency ($f_{\text{RTC}} = f_{\text{OSCm}}/32$). It is therefore independent from the selected clock generation mode of the XC161.

The RTC basically consists of a chain of divider blocks:

- a selectable 8:1 divider (on off)
- the reloadable 16-bit timer T14
- the 32-bit RTC timer block (accessible via registers RTCH and RTCL), made of:
 - a reloadable 10-bit timer
 - a reloadable 6-bit timer
 - a reloadable 6-bit timer
 - a reloadable 10-bit timer

All timers count up. Each timer can generate an interrupt request. All requests are combined to a common node request.



Figure 8 RTC Block Diagram

Note: The registers associated with the RTC are not affected by a reset in order to maintain the correct system time even when intermediate resets are executed.



3.9 A/D Converter

For analog signal measurement, a 10-bit A/D converter with 12 multiplexed input channels and a sample and hold circuit has been integrated on-chip. It uses the method of successive approximation. The sample time (for loading the capacitors) and the conversion time is programmable (in two modes) and can thus be adjusted to the external circuitry. The A/D converter can also operate in 8-bit conversion mode, where the conversion time is further reduced.

Overrun error detection/protection is provided for the conversion result register (ADDAT): either an interrupt request will be generated when the result of a previous conversion has not been read from the result register at the time the next conversion is complete, or the next conversion is suspended in such a case until the previous result has been read.

For applications which require less analog input channels, the remaining channel inputs can be used as digital input port pins.

The A/D converter of the XC161 supports four different conversion modes. In the standard Single Channel conversion mode, the analog level on a specified channel is sampled once and converted to a digital result. In the Single Channel Continuous mode, the analog level on a specified channel is repeatedly sampled and converted without software intervention. In the Auto Scan mode, the analog levels on a prespecified number of channels are sequentially sampled and converted. In the Auto Scan Continuous mode, the prespecified channels are repeatedly sampled and converted. In addition, the conversion of a specific channel can be inserted (injected) into a running sequence without disturbing this sequence. This is called Channel Injection Mode.

The Peripheral Event Controller (PEC) may be used to automatically store the conversion results into a table in memory for later evaluation, without requiring the overhead of entering and exiting interrupt routines for each data transfer.

After each reset and also during normal operation the ADC automatically performs calibration cycles. This automatic self-calibration constantly adjusts the converter to changing operating conditions (e.g. temperature) and compensates process variations.

These calibration cycles are part of the conversion cycle, so they do not affect the normal operation of the A/D converter.

In order to decouple analog inputs from digital noise and to avoid input trigger noise those pins used for analog input can be disconnected from the digital IO or input stages under software control. This can be selected for each pin separately via register P5DIDIS (Port 5 Digital Input Disable).

The Auto-Power-Down feature of the A/D converter minimizes the power consumption when no conversion is in progress.



Table 7 Summary of the XC161's Parallel Ports				
Port	Control	Alternate Functions		
PORT0	Pad drivers	Address/Data lines or data lines ¹⁾		
PORT1	Pad drivers	Address lines ²⁾		
		Capture inputs or compare outputs, Serial interface lines		
Port 2	Pad drivers, Open drain, Input threshold	Capture inputs or compare outputs, Timer control signal, Fast external interrupt inputs		
Port 3	Pad drivers, Open drain, Input threshold	Timer control signals, serial interface lines, Optional bus control signal BHE/WRH, System clock output CLKOUT (or FOUT)		
Port 4	Pad drivers,	Segment address lines ³⁾		
Open drain, Input threshold		CAN/SDLM interface lines ⁴⁾		
Port 5	-	Analog input channels to the A/D converter, Timer control signals		
Port 6	Open drain, Input threshold	Capture inputs or compare outputs, Bus arbitration signals BREQ, HLDA, HOLD, Optional chip select signals		
Port 7	Open drain, Input threshold	Capture inputs or compare outputs, CAN/SDLM interface lines ⁴⁾		
Port 9	Pad drivers,	Capture inputs or compare outputs		
	Open drain, Input threshold	CAN/SDLM interface lines ⁴⁾ , IIC bus interface lines ⁴⁾		
Port 20	Pad drivers, Open drain	Bus control signals RD, WR/WRL, READY, ALE, External access enable <u>pin EA,</u> Reset indication output RSTOUT		

1) For multiplexed bus cycles.

2) For demultiplexed bus cycles.

3) For more than 64 Kbytes of external resources.

4) Can be assigned by software.



Table 8 In	struction Set Summary (cont'd)	
Mnemonic	Description	Bytes
ROL/ROR	Rotate left/right direct word GPR	2
ASHR	Arithmetic (sign bit) shift right direct word GPR	2
MOV(B)	Move word (byte) data	2/4
MOVBS/Z	Move byte operand to word op. with sign/zero extension	2/4
JMPA/I/R	Jump absolute/indirect/relative if condition is met	4
JMPS	Jump absolute to a code segment	4
JB(C)	Jump relative if direct bit is set (and clear bit)	4
JNB(S)	Jump relative if direct bit is not set (and set bit)	4
CALLA/I/R	Call absolute/indirect/relative subroutine if condition is met	4
CALLS	Call absolute subroutine in any code segment	4
PCALL	Push direct word register onto system stack and call absolute subroutine	4
TRAP	Call interrupt service routine via immediate trap number	2
PUSH/POP	Push/pop direct word register onto/from system stack	2
SCXT	Push direct word register onto system stack and update register with word operand	4
RET(P)	Return from intra-segment subroutine (and pop direct word register from system stack)	2
RETS	Return from inter-segment subroutine	2
RETI	Return from interrupt service subroutine	2
SBRK	Software Break	2
SRST	Software Reset	4
IDLE	Enter Idle Mode	4
PWRDN	Enter Power Down Mode (supposes NMI-pin being low)	4
SRVWDT	Service Watchdog Timer	4
DISWDT/ENWE	DT Disable/Enable Watchdog Timer	4
EINIT	End-of-Initialization Register Lock	4
ATOMIC	Begin ATOMIC sequence	2
EXTR	Begin EXTended Register sequence	2
EXTP(R)	Begin EXTended Page (and Register) sequence	2/4
EXTS(R)	Begin EXTended Segment (and Register) sequence	2/4



able 8 Instruction Set Summary (cont'd)				
Mnemonic	Description	Bytes		
NOP	Null operation	2		
CoMUL/CoMAC	Multiply (and accumulate)	4		
CoADD/CoSUB	Add/Subtract	4		
Co(A)SHR	(Arithmetic) Shift right	4		
CoSHL	Shift left	4		
CoLOAD/STORE	Load accumulator/Store MAC register	4		
CoCMP	Compare	4		
CoMAX/MIN	Maximum/Minimum	4		
CoABS/CoRND	Absolute value/Round accumulator	4		
CoMOV	Data move	4		
CoNEG/NOP	Negate accumulator/Null operation	4		





Figure 11 Sleep and Power Down Supply Current due to RTC and Oscillator Running, as a Function of Oscillator Frequency



Figure 12 Sleep and Power Down Leakage Supply Current as a Function of Temperature



4.4 AC Parameters

4.4.1 Definition of Internal Timing

The internal operation of the XC161 is controlled by the internal master clock f_{MC} .

The master clock signal $f_{\rm MC}$ can be generated from the oscillator clock signal $f_{\rm OSC}$ via different mechanisms. The duration of master clock periods (TCMs) and their variation (and also the derived external timing) depend on the used mechanism to generate $f_{\rm MC}$. This influence must be regarded when calculating the timings for the XC161.



Figure 14 Generation Mechanisms for the Master Clock

Note: The example for PLL operation shown in **Figure 14** refers to a PLL factor of 1:4, the example for prescaler operation refers to a divider factor of 2:1.

The used mechanism to generate the master clock is selected by register PLLCON.



CPU and EBC are clocked with the CPU clock signal f_{CPU} . The CPU clock can have the same frequency as the master clock ($f_{CPU} = f_{MC}$) or can be the master clock divided by two: $f_{CPU} = f_{MC}$ / 2. This factor is selected by bit CPSYS in register SYSCON1.

The specification of the external timing (AC Characteristics) depends on the period of the CPU clock, called "TCP".

The other peripherals are supplied with the system clock signal f_{SYS} which has the same frequency as the CPU clock signal f_{CPU} .

Bypass Operation

When bypass operation is configured (PLLCTRL = $0x_B$) the master clock is derived from the internal oscillator (input clock signal XTAL1) through the input- and output-prescalers:

 $f_{MC} = f_{OSC} / ((PLLIDIV+1) \times (PLLODIV+1)).$

If both divider factors are selected as '1' (PLLIDIV = PLLODIV = '0') the frequency of f_{MC} directly follows the frequency of f_{OSC} so the high and low time of f_{MC} is defined by the duty cycle of the input clock f_{OSC} .

The lowest master clock frequency is achieved by selecting the maximum values for both divider factors:

 $f_{\rm MC} = f_{\rm OSC} / ((3 + 1) \times (14 + 1)) = f_{\rm OSC} / 60.$

Phase Locked Loop (PLL)

When PLL operation is configured (PLLCTRL = 11_B) the on-chip phase locked loop is enabled and provides the master clock. The PLL multiplies the input frequency by the factor **F** ($f_{MC} = f_{OSC} \times F$) which results from the input divider, the multiplication factor, and the output divider (**F** = PLLMUL+1 / (PLLIDIV+1 × PLLODIV+1)). The PLL circuit synchronizes the master clock to the input clock. This synchronization is done smoothly, i.e. the master clock frequency does not change abruptly.

Due to this adaptation to the input clock the frequency of $f_{\rm MC}$ is constantly adjusted so it is locked to $f_{\rm OSC}$. The slight variation causes a jitter of $f_{\rm MC}$ which also affects the duration of individual TCMs.

The timing listed in the AC Characteristics refers to TCPs. Because $f_{\rm CPU}$ is derived from $f_{\rm MC}$, the timing must be calculated using the minimum TCP possible under the respective circumstances.

The actual minimum value for TCP depends on the jitter of the PLL. As the PLL is constantly adjusting its output frequency so it corresponds to the applied input frequency (crystal or oscillator) the relative deviation for periods of more than one TCP is lower than for one single TCP (see formula and **Figure 15**).

This is especially important for bus cycles using waitstates and e.g. for the operation of timers, serial interfaces, etc. For all slower operations and longer periods (e.g. pulse train



4.4.2 On-chip Flash Operation

The XC161's Flash module delivers data within a fixed access time (see Table 17).

Accesses to the Flash module are controlled by the PMI and take 1+WS clock cycles, where WS is the number of Flash access waitstates selected via bitfield WSFLASH in register IMBCTRL. The resulting duration of the access phase must cover the access time t_{ACC} of the Flash array. Therefore, the required Flash waitstates depend on the available speed grade as well as on the actual system frequency.

Note: The Flash access waitstates only affect non-sequential accesses. Due to prefetching mechanisms, the performance for sequential accesses (depending on the software structure) is only partially influenced by waitstates.

In typical applications, eliminating one waitstate increases the average performance by 5% ... 15%.

Parameter	Symb	ol	Limit Values			Unit
			Min.	Тур.	Max.	
Flash module access time	t _{ACC}	CC	_	-	50	ns
Programming time per 128-byte block	t _{PR}	CC	_	2 ¹⁾	5	ms
Erase time per sector	t _{ER}	CC	-	200 ¹⁾	500	ms

Table 17 Flash Characteristics (Operating Conditions apply)

1) Programming and erase time depends on the system frequency. Typical values are valid for 40 MHz.

Example: For an operating frequency of 40 MHz (clock cycle = 25 ns), devices can be operated with 1 waitstate: $((1+1) \times 25 \text{ ns}) \ge 50 \text{ ns}$.

 Table 18 indicates the interrelation of waitstates and system frequency.

Table 18Flash Access Waitstates

Required Waitstates	Frequency Range
$\overline{0 \text{ WS (WSFLASH = } 00_B)}$	$f_{\rm CPU} \le 20 \ { m MHz}$
1 WS (WSFLASH = 01 _B)	$f_{\rm CPU} \le 40 \ { m MHz}$

Note: The maximum achievable system frequency is limited by the properties of the respective derivative, i.e. 40 MHz (or 20 MHz for xxx-16F20F devices).



4.4.3 External Clock Drive XTAL1

Table 19External Clock Drive Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit	Unit	
			Min.	Max.	
Oscillator period	t _{OSC}	SR	25	250 ¹⁾	ns
High time ²⁾	<i>t</i> ₁	SR	6	_	ns
Low time ²⁾	<i>t</i> ₂	SR	6	_	ns
Rise time ²⁾	t ₃	SR	_	8	ns
Fall time ²⁾	<i>t</i> ₄	SR	_	8	ns

1) The maximum limit is only relevant for PLL operation to ensure the minimum input frequency for the PLL.

2) The clock input signal must reach the defined levels $V_{\rm ILC}$ and $V_{\rm IHC}$.



Figure 16 External Clock Drive XTAL1

Note: If the on-chip oscillator is used together with a crystal or a ceramic resonator, the oscillator frequency is limited to a range of 4 MHz to 16 MHz.

It is strongly recommended to measure the oscillation allowance (negative resistance) in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the limits specified by the crystal supplier.

When driven by an external clock signal it will accept the specified frequency range. Operation at lower input frequencies is possible but is verified by design only (not subject to production test).





Figure 20 Multiplexed Bus Cycle



Package and Reliability



You can find all of our packages, sorts of packing and others in our Infineon Internet Page "Products": http://www.infineon.com/products. Dimensions in mm